

T11, Fibre Channel Interfaces Liaison Report

August, 2003

- TC T11 last met August 14, 2003.

65 representatives of 56 organizations attended. The total number of member organizations is 59.

HIPPI-6400-OPT was published.

A letter ballot approving an interpretation for SBCON was initiated.

ISO actions included approval of RapidIO, a new work item for FC-MJSQ, and approval of the transfer of four projects to IEEE.

T11 took all the requested actions of its TGs as described below.

- TG T11.2 - FC physical layer TG:
Membership is 42 companies.

Projects in the approval stage include FC-PI-2, 10GFC, and FC-MJSQ.

The project proposal for FC-PI-4 was requested and approved.

Projects in development include FCSM-2, and FC-PI-3.

Optical activities of special interest included 1310 nm 1 km link, Electronic Dispersion Control (EDC). The bi-directional optical work was removed from FC-PI-3. Copper activities of special interest included reports on signal integrity.

A total of 9 teleconferences were authorized to: continue development on EDC, resolve FC-MJSQ comments, FC-PI-2, and additional optical variants for FC-PI-3.

- T11.3 - FC logical / protocol TG
Membership is 47 companies.

FC-BB-2 was published.

Projects in the approval stage include:
FC-SB-3, FC-FS, FC-GS-4, and FC-SW-3.

Project proposals for FC-AE-ASM, FC-AE-1553, FC-AE-LP, and FC-AE-RDMA were forwarded.

Projects in the development phase include:
FC-FS-2, FC-AE-2, FC-BB-3, FC-LS,
FC-DA, FC-MI-2, and FC-SP.

The fabric expansion study group and conformance study group are ongoing.

Interim adhoc for FC-SW-3 and FC-GS-4 in Boulder, CO, August 23 and 24 were approved. An interim adhoc for FC-SP was approved for September 9 at the Seattle T10 conference.

- T11.5, storage network management TG
Membership is 35 companies.

The FC-SWAPI project is in approval.

The FC-HBA, FAIS, SM-MM, and SM-AMD projects are in development.

An interim adhoc for FAIS in Seattle at the T10 meeting site was scheduled for September 10.

An interim teleconference was authorized for SM-MM and SM-AMD

- T11 TC and TG liaisons

Liaisons are presently distributed as follows:

T11: INCITS, T10, FCIA, T1X1.5

T11.2: T11, SFF SSWG on Transceivers, SFF/HSS, FCIA, IEEE802.3 activities including: 10GBASE-CX4, 10GBASE-T, 10GBE EFM, EDC adhoc.

T11.3: T11, Joint T10/T11 on FCP-3, 10GFC, IETF IPS, IETF IPv6 over FC, FCIA, T1X1.

T11.5: T11, DMTF, IETF, SNIA.

- Next meeting

T11 Plenary Week, October 6-9, 2003, in Oklahoma City, OK. Meeting map and hotel information are available at www.t11.org.

- For more details, minutes, and meeting schedules, see www.t11.org.